AMENDMENTS TO THE CLAIMS

1. (Previously Presented) A method, comprising:

forming a metal particle of a size suitable for use as a catalyst in forming a nanotube by an electroless process in a bath; and

once formed, depositing the particle on a semiconductor substrate.

2. (Canceled)

3. (Original) The method of claim 2, wherein the forming a metal particle comprises introducing an ionic precursor of the metal particle into a bath and reducing the ionic precursor by chemical reaction.

4. (Original) The method of claim 1, wherein forming the metal particle comprises forming an alloy.

5, (Original) The method of claim 4, wherein forming the alloy comprises forming a Group VIII metal alloy.

6. (Original) The method of claim 4, wherein forming the alloy comprises forming a Group VI metal alloy.

7. (Original) The method of claim 4, wherein forming the alloy comprises forming an alloy including a Group VIII metal and a Group VI metal.

Claims 8-35 (Canceled)

36. (Previously Presented) The method of claim 1, wherein prior to depositing the particle, the method further comprises immersing the substrate in the bath.

37. (Previously Presented) The method of claim 1, wherein depositing the particle comprises dispensing the bath comprising the particle on the substrate.

38. (Previously Presented) The method of claim 1, wherein prior to depositing the particle, the method comprises extracting the particle from the bath.

39. (Previously Presented) The method of claim 1, wherein forming a metal particle in a bath comprises mixing metal ions from Group VIII and metal ions from Group VI with one or more reducing agents.

40. (Previously Presented) The method of claim 39, wherein the one or more reducing agents are alkaline metal-free reducing agents.